Special Issue

Applications of Data Sciences in Semiconductor Industry: Design, Manufacturing, Packaging and Testing

Message from the Guest Editors

With the rapid development of artificial intelligence in both hardware and software, the demand for semiconductors has highly increased in volume as well as function. The semiconductor theme mainly contains design, manufacturing, packaging, and testing. At the same time, the new advancements in information technology and information systems have also advanced data sciences including optimization, data mining, machine learning, deep learning, and artificial intelligence. The use of data sciences to perform data analysis represents an effective and efficient trend in many fields. The objective of this Special Issue is to utilize the latest data science techniques in the semiconductor industry, including design, manufacturing, packaging, and testing. The scope of this Special Issue is based on the application of data science approaches in coping with semiconductor industry issues.

Guest Editors

Prof. Dr. Ping-Feng Pai
Department of Information Management, National Chi Nan University, Nantou 54561, Taiwan

Prof. Dr. Yu-Po Wang
1. Siliconware Precision Industries Co., Ltd. (SPIL), Taichung 42749, Taiwan
2. Bachelor of Science and Technology, National Chi Nan University, Nantou 54561, Taiwan

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Micromachines
Editorial Office
MDPI, Grosspeteranlage 5
4052 Basel, Switzerland
Tel: +41 61 683 77 34
micromachines@mdpi.com

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Editor-in-Chief

Prof. Dr. Ai-Qun Liu

1. Department of Electrical and Electronic Engineering, The Hong Kong Polytechnic University, Hong Kong, China
2. School of Electrical and Electronic Engineering, Nanyang Technological University, Singapore 639798, Singapore

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